

**Amendments To The Claims:**

Claims 1-9 (Canceled).

10. (Previously Presented) A method for producing an electronic module with an integrated electromagnetic shield having a network of interconnection balls and shielding balls (7) or preforms which are geometrically identical and surface-mounted components (2) on a substrate (1), said substrate having a mounting surface having predetermined mounting lands for the interconnection balls and shielding balls (7) and surface-mounted components and said surface-mounted components being electronic devices used for ensuring electronic function, the method including:

depositing soldering cream (8) onto the mounting lands for the surface-mounted components and the interconnection balls and shielding balls, which are to be located on the mounting surface of the substrate, simultaneously;

transferring the surface-mounted components onto the deposited soldering cream on the corresponding mounting lands;

transferring the interconnection balls and shielding balls collectively onto the deposited soldering cream on the corresponding mounting lands on the mounting surface, which is the same side of the substrate as for the surface-mounted components; and

soldering with a single reflow cycle the surface-mounted components and the interconnection balls and shielding balls onto the substrate, simultaneously, such that the electronic module is in the shape of a ball housing and is directly connectable to the printed circuit and that the shielding balls insure the electromagnetic shielding of the components situated on the lower face of the substrate among the interconnection balls and shielding balls.

11. (Previously Presented) The method as claimed in claim 10, wherein the soldering cream (8) is deposited via serigraphy.

12. (Previously Presented) The method as claimed in claim 10, wherein the soldering cream (8) is deposited by syringe.

13. (Canceled)

14. (Previously Presented) The method as claimed in claim 10, wherein the components (2)

located on the lower face of the substrate 1 among the interconnection balls and shielding balls are decoupling capacitors (17) and/or serial resistors (16) and/or filtering cells and/or quartz adapter condensers are/is integrated as close to the interconnection balls and shielding balls (7) as possible and on the mounting surface of the electronic module.

15. (Currently Amended) The method as claimed in claims 10, the electronic module having a gripping surface, wherein ~~the gripping of the electronic module may be gripped by suction~~ the transferring step includes gripping the gripping surface of the module by vacuum suction and ~~transferred~~ transferring it to the printed circuit.

Claims 16-18 (Canceled).

19. (Currently Amended) The method as claimed in claim 10, ~~the electronic module being directly connectable by soldering to the printed circuit~~ wherein the soldering step further comprises directly connecting the module to the substrate.

20. (Previously Presented) The method as claimed in claim 10, wherein the interconnection balls and shielding balls have a diameter greater than the height of said surface-mounted components.